

Features

- The plastic package carries UL Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed:260°C/10 seconds at terminals


Mechanical Characteristics

- Case: SMA(DO-214AC) package molded plastic body over passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0021 ounce, 0.059 grams

Absolute Maximum Ratings and Electrical Parameters (TA=25°C unless otherwise specified)

PARAMETER	SYMBOL	ES1A	ES1B	ES1C	ES1D	ES1E	ES1G	ES1J	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{AV}	1							A
Peak forward surge current	I_{FSM}	30							A
Maximum instantaneous forward voltage at 1A	V_F	0.95					1.25	1.7	V
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^\circ\text{C}$	I_R	5						μA
	$T_A=100^\circ\text{C}$	I_{RT}	50						μA
Maximum reverse recovery time ^(NOTE 1)	t_{rr}	35						ns	
Typical junction capacitance ^(NOTE 2)	C_J	15						pF	
Typical Thermal Resistance Junction to Ambient ^(NOTE3)	$R_{\theta JA}$	85						$^\circ\text{C}/\text{W}$	
Typical Thermal Resistance Junction to Lead ^(NOTE3)	$R_{\theta JL}$	28						$^\circ\text{C}/\text{W}$	
Operating Temperature Range	T_J	-55 to 150						$^\circ\text{C}$	
Storage Temperature Range	T_{STG}	-55 to 150						$^\circ\text{C}$	

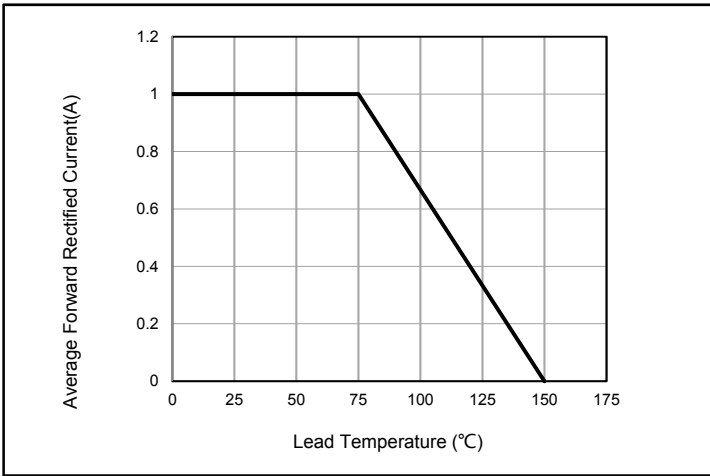
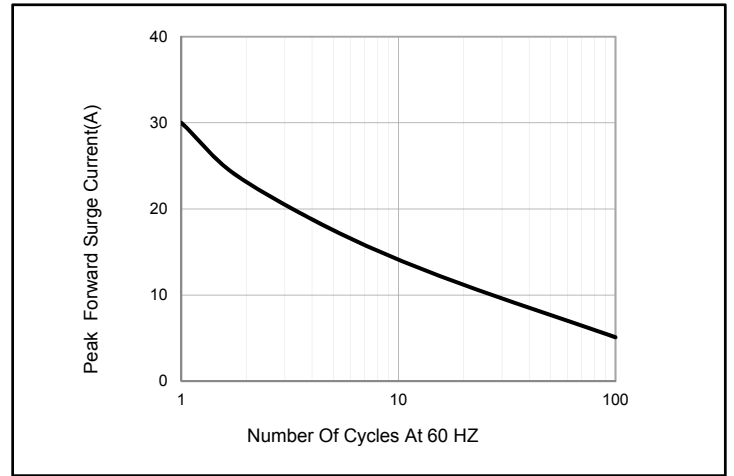
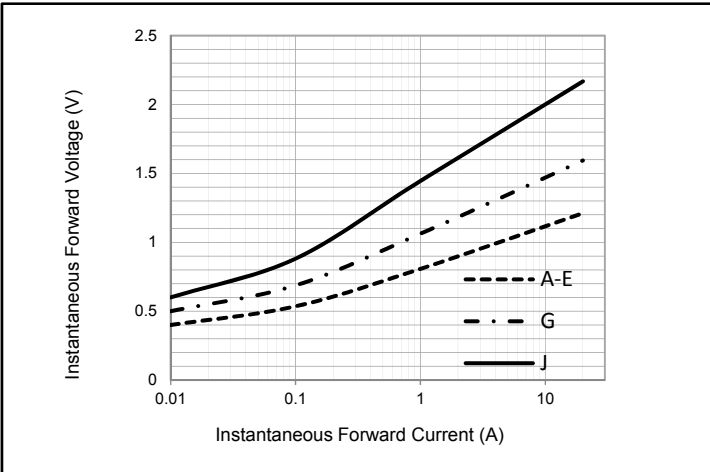
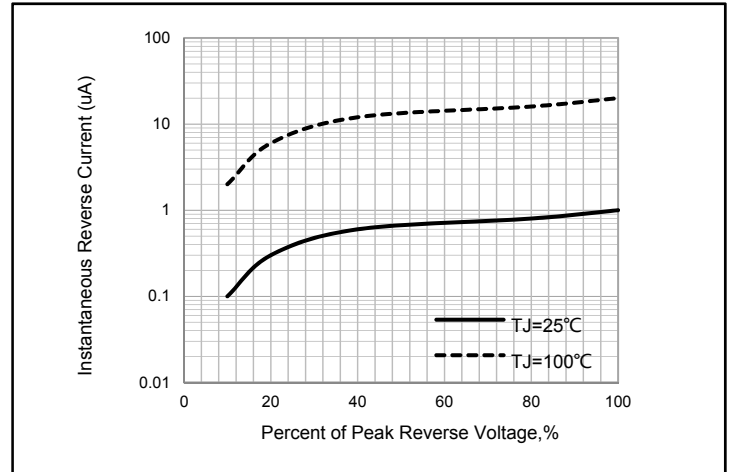
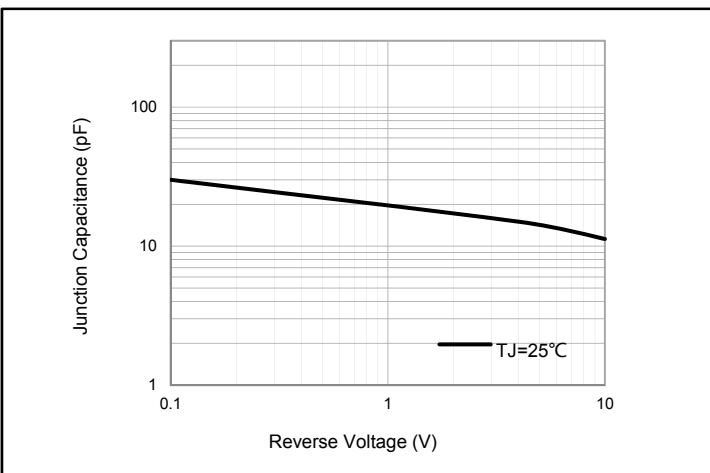
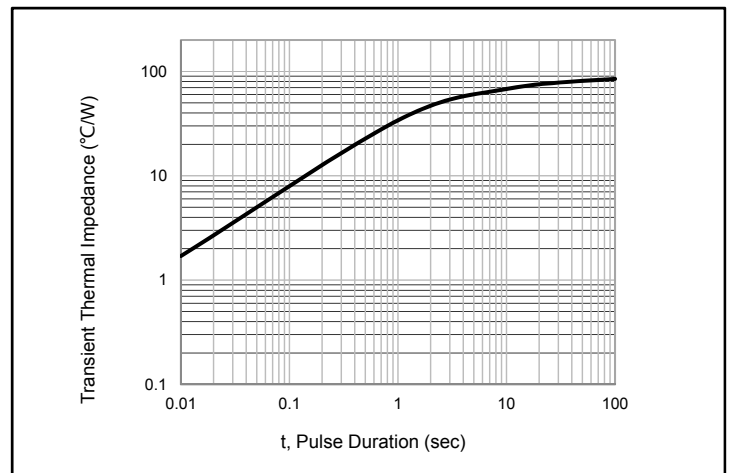
Note1: Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$

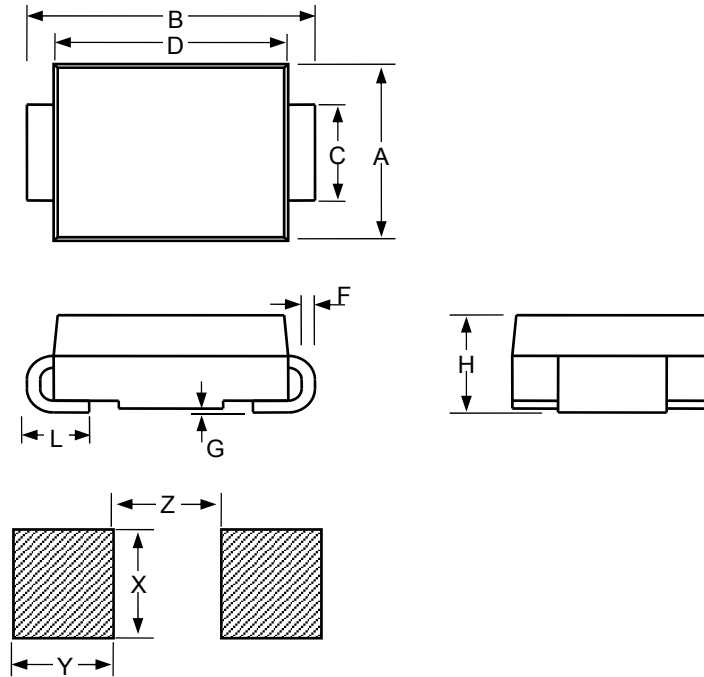
Note2: Measured at 1MHz and applied reverse voltage of 4.0V DC.

Note3: PCB. mounted with 5×5mm copper pad areas

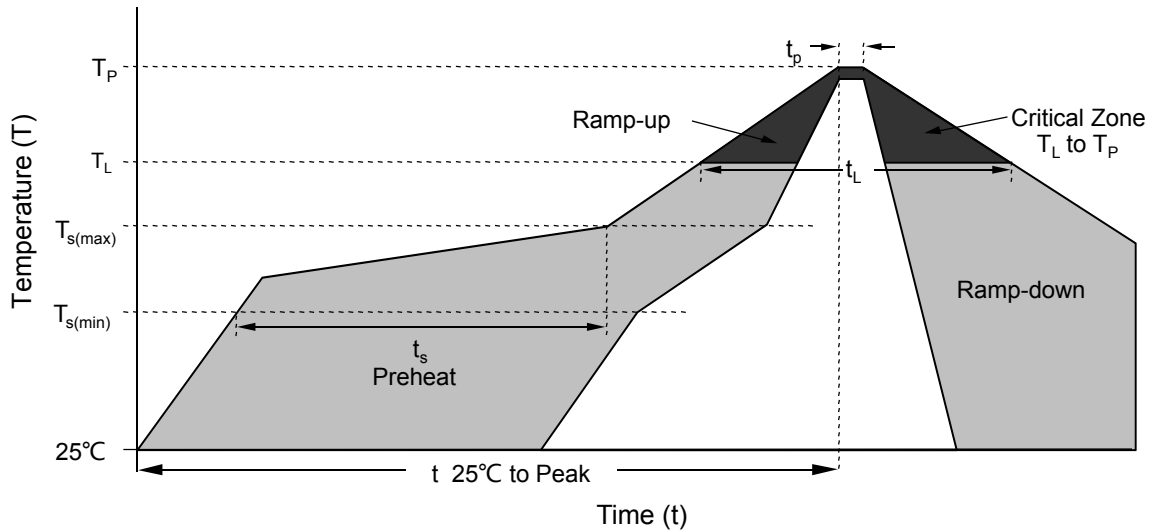
Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SMA	Tape/Reel, 11" reel	5000	EIA-481-1
	Tape/Reel, 7" reel	2000	EIA-481-1

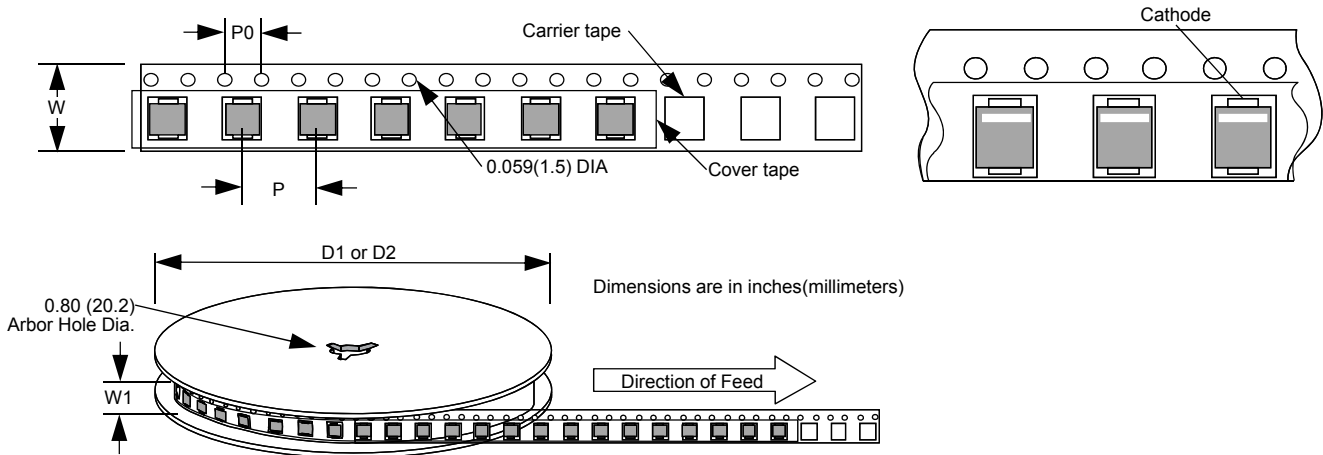

Fig. 1 - Forward Current Derating Curve

Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

Fig. 3 - Typical Instantaneous Forward Characteristics

Fig. 4 - Typical Reverse Characteristics

Fig. 5 - Typical Junction Capacitance

Fig. 6 - Typical Transient Thermal Impedance



SMA						
Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.1		0.11	2.54		2.8
B	0.194		0.223	4.93		5.66
C	0.051		0.067	1.3		1.7
D	0.157		0.177	3.99		4.5
L	0.03		0.06	0.76		1.52
F	0.006		0.012	0.152		0.305
G	-		0.008	-		0.203
H	0.078		0.095	1.98		2.42
X		0.085			2.16	
Y		0.07			1.78	
Z		0.079			2	



Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (t_L)	60 – 150 secs
Peak Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 secs
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (t)		8 minutes Max.
Do not exceed		260°C



Dimensions are in inches(millimeters)

Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
P		0.157			4	
P0		0.157			4	
W		0.472			12	
W1		0.492			12.5	
D1		7			177.8	
D2		11			279.4	

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